



MX555ABD100M000

Ultra-Low Jitter 100MHz HCSL XO

ClockWorks® FUSION

General Description

The MX555ABD100M000 is an ultra-low phase jitter XO with HCSL output optimized for high line rate applications.

Applications

- PCI Express
- High Speed ADC/DAC
- Storage

Absolute Maximum Ratings¹

| | |
|--|-----------------|
| Supply Voltage (VIN)..... | +4.6V |
| Lead Temperature (soldering, 10s)..... | 260°C |
| Case Temperature..... | 115°C |
| Storage Temperature (T _s)..... | -65°C to +125°C |
| ESD Machine Model..... | 200V |
| ESD Rating (HBM)..... | 2kV |

Electrical Characteristics

VDD = 2.5V ±5% or 3.3V ±10%, -40°C to +85°C, outputs terminated with 50 Ohms to VSS.³

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Units |
|--------|-----------------------------------|---|-----------|------------|-----------|-------|
| IDD | Supply Current | | | | 95 | mA |
| F0 | Center Frequency | | | 100 | | MHz |
| | Frequency Stability | Note 4 | | | ±50 | ppm |
| ∅j | Phase Noise | Integration Range (12kHz to 20MHz) Integration Range (1MHz to 20MHz) | | 135 109 | 200 | fsRMS |
| Tstart | Start-Up Time | | | | 10 | ms |
| TR/TF | Rise/Fall time | 20%-80% | 150 | 300 | 450 | ps |
| | Duty Cycle | | 48 | 50 | 52 | % |
| VOH | Output High Voltage | HCSL output levels | 660 | 700 | 850 | mV |
| VOL | Output Low Voltage | HCSL output levels | -150 | 0 | 27 | mV |
| VOVS | Max Output Including Overshoot | | | | VOH + 0.3 | V |
| VUDS | Min Output Including Undershoot | | VOL - 0.3 | | | V |
| VRB | Ringback Voltage | | 0.2 | | | V |
| VOX | Absolute Crossing Point | | 250 | 350 | 550 | mV |
| Vswing | Peak to Peak Output Voltage Swing | | 640 | 700 | 950 | mV |

Notes:

1. Exceeding the absolute maximum ratings may damage the device.
2. The device is not guaranteed to function outside its operating ratings.
3. Guaranteed after thermal equilibrium.
4. Inclusive of initial accuracy, temperature drift, aging, shock, vibration.

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Features

- 100MHz HCSL
- PCIe Gen 1/2/3/4/5 Compliant
- Typical phase noise:
 - 109fs (Integration range: 1MHz-20MHz)
- ±50ppm total frequency stability
- -40°C to +85°C temperature range
- Industry standard 6-Pin 5mm x 3.2mm LGA package

Operating Ratings²

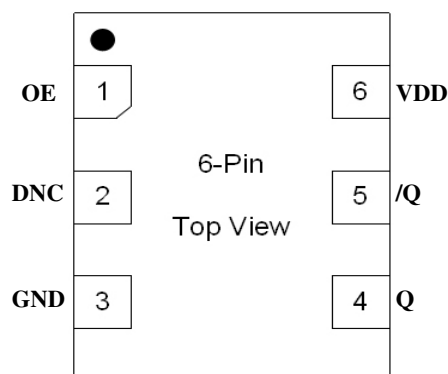
| | |
|---------------------------------------|-------------------|
| Supply Voltage (VIN)..... | +2.375V to +3.63V |
| Ambient Temperature (TA)..... | -40°C to +85°C |
| Junction Thermal Resistance | |
| LGA (T _{JC}) Still Air..... | 58°C/W |

Ordering Information

| Ordering Part Number | Marking Line 1 | Marking Line 3 | Shipping | Package |
|----------------------|----------------|----------------|---------------|-----------------------|
| MX555ABD100M000 | MX555A | BD1000 | Tube | 6-Pin 5mm x 3.2mm LGA |
| MX555ABD100M000-TR | MX555A | BD1000 | Tape and Reel | 6-Pin 5mm x 3.2mm LGA |

Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

Pin Configuration



Pin Description

| Pin Number | Pin Name | Pin Type | Pin Level | Pin Function |
|------------|----------|----------|-----------|---|
| 1 | OE | I, SE | LVC MOS | Output Enable, disables output to tri-state, 0 = Disabled, 1 = Enabled, 50k Ohms Pull-Up (Internal) |
| 2 | DNC | | | Make no connection, leave floating. |
| 3 | GND | PWR | | Power Supply Ground |
| 4, 5 | Q, /Q | O, Diff | HCSL | Clock Output Frequency = 100MHz |
| 6 | VDD | PWR | | Power Supply |

Environmental Specifications

| | |
|------------------------------|--|
| Thermal Shock | MIL-STD-883, Method 1011, Condition A |
| Moisture Resistance | MIL-STD-883, Method 1004 |
| Mechanical Shock | MIL-STD-883, Method 2002, Condition C |
| Mechanical Vibration | MIL-STD-883, Method 2007, Condition A |
| Resistance to Soldering Heat | J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max) |
| Hazardous Substance | Pb-Free / RoHS / Green Compliant |
| Solderability | JESD22-B102-D Method 2 (Preconditioning E) |
| Terminal Strength | MIL-STD-883, Method 2004, Test Condition D |
| Gross Leak | MIL-STD-883, Method 1014, Condition C |
| Fine Leak | MIL-STD-883, Method 1014, Condition A2, R1=2x10 ⁻⁸ atm cc/s |
| MSL Level | Crystal - MSL-1, Package MSL-3 |
| Solvent Resistance | MIL-STD-202, Method 215 |

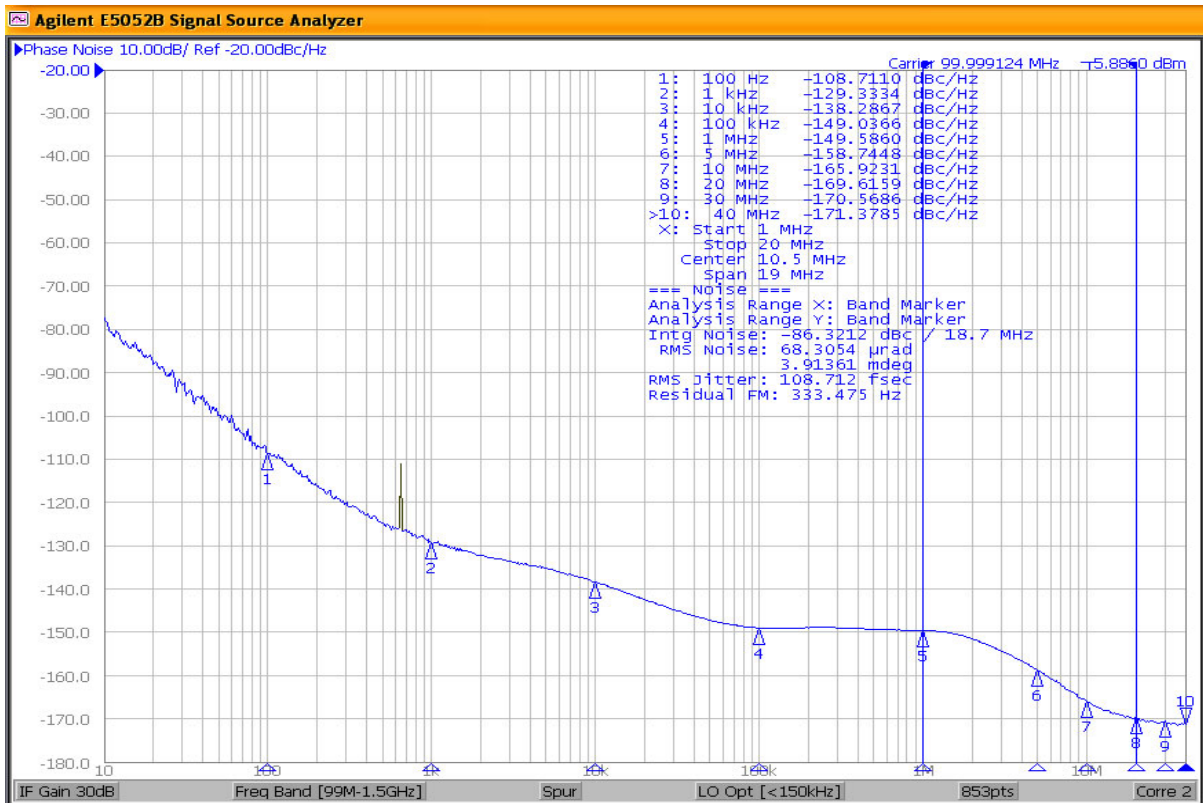


Figure 1. HCSL Output 100MHz 1MHz-20MHz 109fs

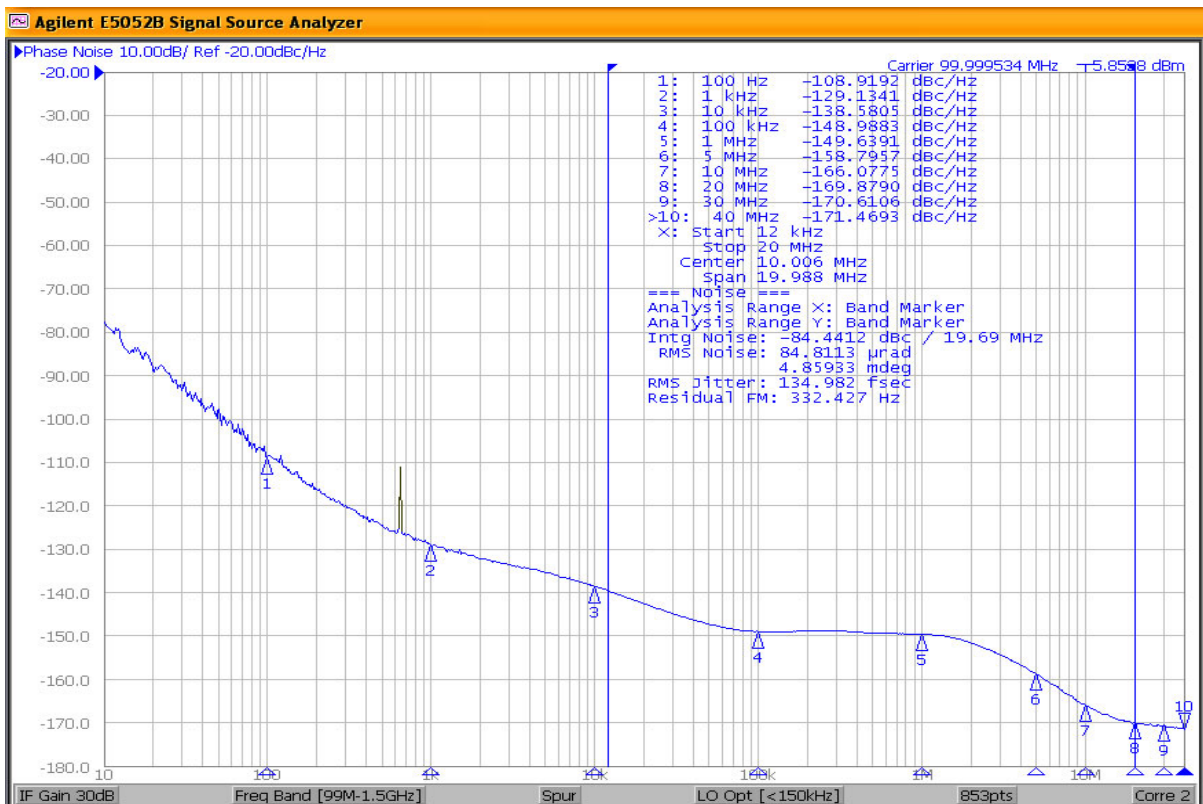


Figure 2. HCSL Output 100MHz 12kHz-20MHz 135fs

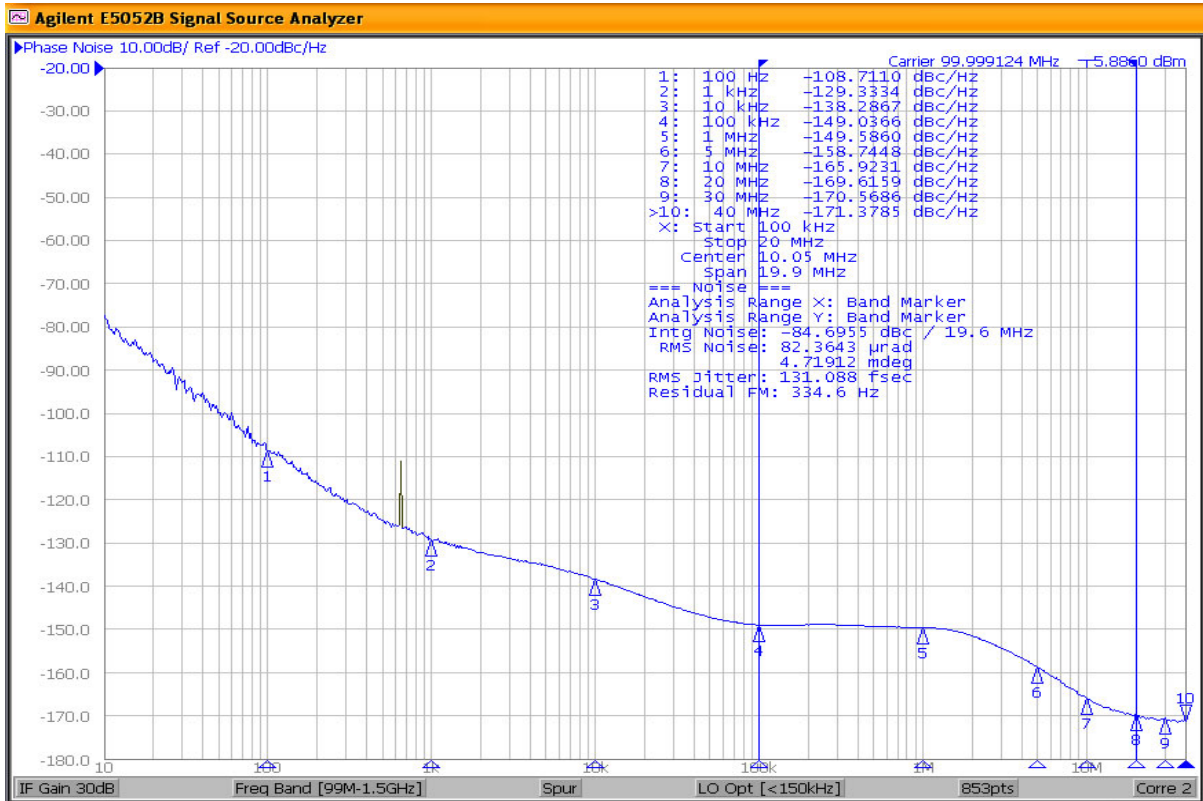
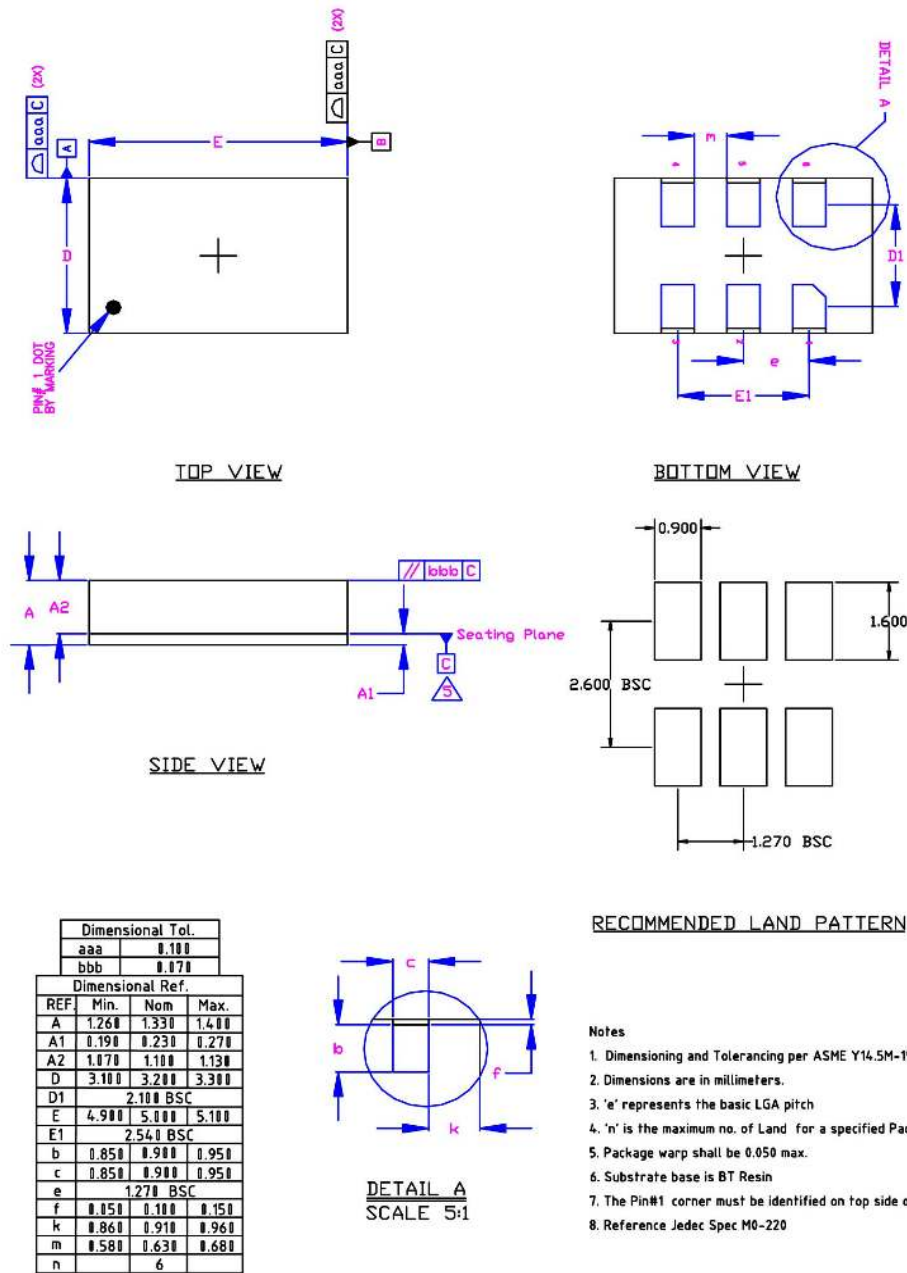


Figure 1. HCSL Output 100MHz 100kHz-20MHz 131fs

Package Information and Recommended Land Pattern for 6-Pin LGA³



RECOMMENDED LAND PATTERN

- Notes**
1. Dimensioning and Tolerancing per ASME Y14.5M-1994.
 2. Dimensions are in millimeters.
 3. 'e' represents the basic LGA pitch
 4. 'n' is the maximum no. of Land for a specified Package.
 5. Package warp shall be 0.050 max.
 6. Substrate base is BT Resin
 7. The Pin#1 corner must be identified on top side only.
 8. Reference Jeduc Spec M0-220

Note:

3. Package information is correct as of the publication date. For updates and most current information, go to www.microchip.com.

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